The Heat Is On 2012

Revolutionary and Evolutionary Innovations in Thermal Management

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The Heat is On 2012: Revolutionary and Evolutionary Innovations in Thermal Management

CONTENTS Agenda **Table Top Exhibitor Directory** Participant Biographies SESSION ONE: PHYSICAL PHENOMENA Kenneth E. Goodson, Ph.D., Stanford University John R. Thome, Ph.D., Professor, Ecole Polytechnique Fédérale de Lausanne (EPFL) The Importance of Modeling Thermal Package Stresses in MEMS Devices """, John Bloomsburgh, Principal Engineer, MEMS Design, Fairchild Semiconductor SESSION TWO: PRODUCTS AND APPLICATIONS A Data Center Environmental Advisory System) % Niru Kumari, Ph.D., Research Scientist, Sustainable Ecosystem Research Group, HP Labs, Hewlett-Packard Co. Thermal Design for High Light Flux LED Products $^{\cdots\cdots *}\%$ Brandon Noska, Applications Engineer, Bridgelux, Inc. Innovations in Flexible Graphite for Thermal Management Applications "+" Martin D. Smalc, Research Associate, GrafTech International Holdings, Inc. **KEYNOTE:** Veerendra Mulay, Ph.D., Thermal Engineer, Hardware Design, Facebook SESSION THREE: EVOLUTIONARY DEVELOPMENTS George Meyer, Chief Operating Office/Chief Technical Officer, Celsia Technologies James M. Marder, Ph.D., Vice President, Material and Process Development, Thermacore, Inc. Design Considerations for Implementing Microscale Thermoelectrics in Thermal Management Applications "% + David A. Koester, VP of Engineering, Nextreme Thermal Solutions, Inc. SESSION FOUR: REVOLUTIONARY DEVELOPMENTS SynJet Augmented Cooling for Cloud Computing% + Raghav Mahalingam, Ph.D., Founder and Chief Scientist, Nuventix, Inc. Transient Through-Silicon Hotspot Imaging % -Kazuaki Yazawa, Ph.D., Research Scientist, Microsanj, LLC Performance Comparison of Novel Thin Miniaturized Piezo Actuated Dual Cooled Jet%+ Peter de Bock, Electronics Cooling Researcher, GE Global Research